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ABSTRACT



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The invention provides an IC socket of synthetic resin, whose surface resistivity is strictly controlled to the desired level and which is much more improved in terms of electrical insulation properties, mechanical properties, heat resistance, chemical resistance, dimensional stability, etc. The IC socket is obtained by molding or otherwise forming a thermoplastic resin composition comprising 40 to 94% by mass of a thermoplastic resin, 5 to 30% by mass of a carbon precursor having a volume resistivity of 10^2 to 10^{10} $\Omega \cdot \text{cm}$ and 1 to 30% by mass of an electrical conductive filler having a volume resistivity of less than 10^2 $\Omega \cdot \text{cm}$.